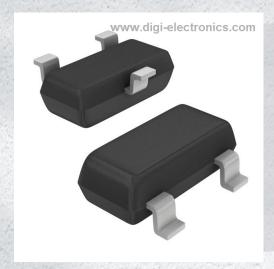


## NTR4501NT1G Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number NTR4501NT1G-DG

Manufacturer onsemi

Manufacturer Product Number NTR4501NT1G

Description MOSFET N-CH 20V 3.2A SOT23-3

Detailed Description N-Channel 20 V 3.2A (Ta) 1.25W (Tj) Surface Mount

SOT-23-3 (TO-236)



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



## **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
NTR4501NT1G	onsemi
Series:	Product Status:
	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
20 V	3.2A (Ta)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ Id, Vgs:
1.8V, 4.5V	80m0hm @ 3.6A, 4.5V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
1.2V @ 250µA	6 nC @ 4.5 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±12V	200 pF @ 10 V
FET Feature:	Power Dissipation (Max):
	1.25W (Tj)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Surface Mount
Supplier Device Package:	Package / Case:
SOT-23-3 (TO-236)	TO-236-3, SC-59, SOT-23-3
Base Product Number:	
NTD4E01	

## **Environmental & Export classification**

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



# MOSFET - Power, Single N-Channel, SOT-23 20 V, 3.2 A

## NTR4501N, NVR4501N

#### **Features**

- Leading Planar Technology for Low Gate Charge / Fast Switching
- 2.5 V Rated for Low Voltage Gate Drive
- SOT-23 Surface Mount for Small Footprint
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Applications**

- Load/Power Switch for Portables
- Load/Power Switch for Computing
- DC-DC Conversion

#### MAXIMUM RATINGS (T<sub>J</sub>= 25°C unless otherwise stated)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	20	V
Gate-to-Source Voltage			V <sub>GS</sub>	±12	V
Continuous Drain	Steady T <sub>A</sub> = 25°C		I <sub>D</sub>	3.2	Α
Current (Note 1)	State	State T <sub>A</sub> = 85°C		2.4	Α
Steady State Power Dissipation (Note 1)	Steady State		P <sub>D</sub>	1.25	W
Pulsed Drain Current	t <sub>p</sub> = 10 μs		I <sub>DM</sub>	10.0	Α
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Continuous Source Current (Body Diode)		Is	1.6	Α	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C	

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	100	°C/W
Junction-to-Ambient (Note 2)	$R_{\theta JA}$	300	

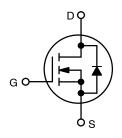
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).
- 2. Surface-mounted on FR4 board using the minimum recommended pad size.

1

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Typ	I <sub>D</sub> Max (Note 1)
20 V	70 mΩ @ 4.5 V	3.6 A
	88 mΩ @ 2.5 V	3.1 A

#### N-Channel



#### 3 1 2 SOT-23

#### 2 SOT-23 CASE 318 STYLE 21

# MARKING DIAGRAM & PIN ASSIGNMENT Drain



TR1 = Device Code for NTR4501N VR1 = Device Code for NVR4501N

M = Date Code\*
■ Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NVR4501NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

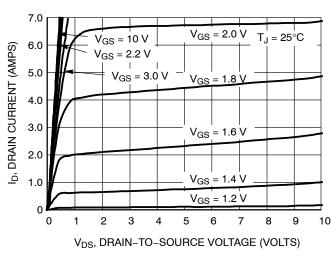
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

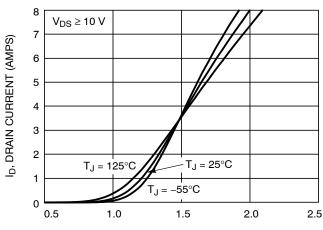
#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
OFF CHARACTERISTICS	•		•	•	•	•
Drain-to-Source Breakdown Voltage (Note 3)	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20	24.5		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>			22		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, T <sub>J</sub> = 25°C			1.5	μΑ
		V <sub>DS</sub> = 16 V, T <sub>J</sub> = 85°C			10	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage (Note 3)	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 250 \mu A$	0.65		1.2	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>			-2.3		mV/°C
Drain-to-Source On Resistance	_	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.6 A		70	80	mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 3.1 A		88	105	1
Forward Transconductance	9FS	V <sub>DS</sub> = 5.0 V, I <sub>D</sub> = 3.6 A		9		S
CHARGES AND CAPACITANCES						
Input Capacitance	C <sub>iss</sub>			200		pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 10 \text{ V}$		80		
Reverse Transfer Capacitance	C <sub>rss</sub>	TDS 15 1		50		
Total Gate Charge	Q <sub>G(TOT)</sub>			2.4	6.0	nC
Gate-to-Source Gate Charge	Q <sub>GS</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V},$ $I_D = 3.6 \text{ A}$		0.5		
Gate-to-Drain Charge	$Q_{GD}$	.5 5.571		0.6		
SWITCHING CHARACTERISTICS (Note 4)						
Turn-On Delay Time	t <sub>d(on)</sub>			6.5	13	ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V,		12	24	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = 3.6 \text{ A}, R_G = 6.0 \Omega$		12	24	
Fall Time	t <sub>f</sub>			3	6	
SOURCE-DRAIN DIODE CHARACTERISTICS	3					
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0 \text{ V}, I_{SD} = 1.6 \text{ A}$		0.8	1.2	V
Reverse Recovery Time	t <sub>RR</sub>			7.1		ns
Charge Time	ta	$V_{GS} = 0 \text{ V},$		5		
Discharge Time	t <sub>b</sub>	$d_{IS}/d_t = 100 \text{ A}/\mu\text{s},$ $I_S = 1.6 \text{ A}$		1.9		
Reverse Recovery Charge	Q <sub>RR</sub>			3.0		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions performance may not be indicated by the Electrical Characteristics if operated under different conditions.
Pulse Test: Pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**





V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS) Figure 2. Transfer Characteristics

Figure 1. On-Region Characteristics

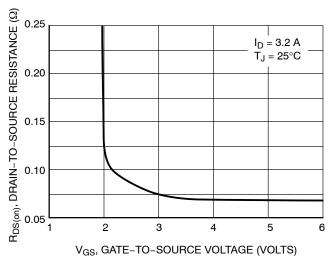


Figure 3. On-Resistance vs. Gate-to-Source Voltage

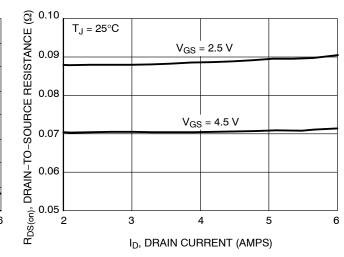


Figure 4. On-Resistance vs. Drain **Current and Gate Voltage** 

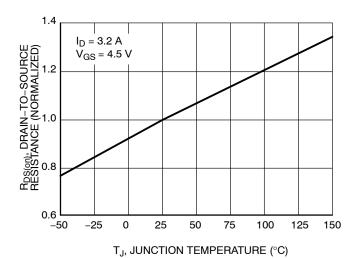
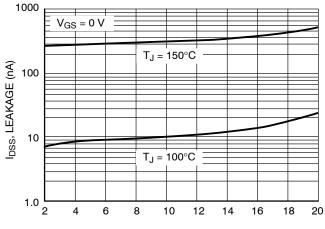


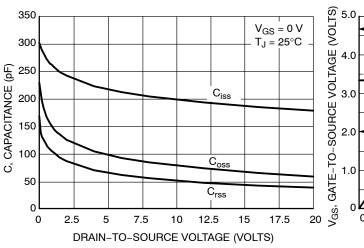
Figure 5. On-Resistance Variation with **Temperature** 



V<sub>DS</sub>, DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 6. Drain-to-Source Leakage Current vs. Voltage

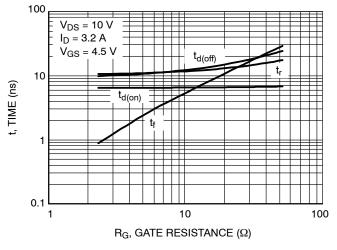
#### **TYPICAL CHARACTERISTICS**



V<sub>DS</sub> DRAIN-TO-SOURCE VOLTAGE (VOLTS)  $V_{DS}$  $V_{GS}$ ← Q<sub>GS</sub> Q<sub>GD</sub>  $T_J = 25^{\circ}C$ I<sub>D</sub> = 3.2 A 0 0.5 1.0 1.5 2.0 2.5 3.0 Q<sub>G</sub>, TOTAL GATE CHARGE (nC)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge



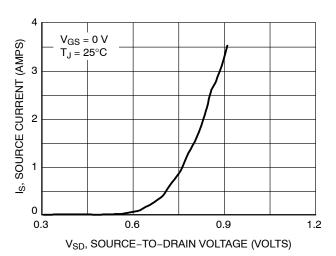


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

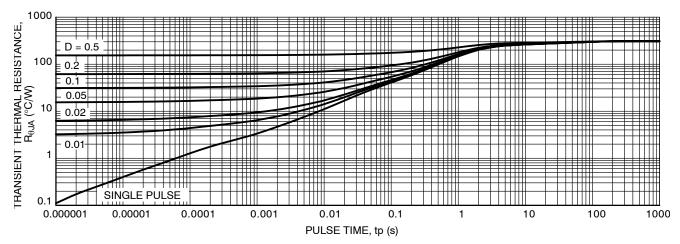


Figure 11. Thermal Response

#### TYPICAL CHARACTERISTICS

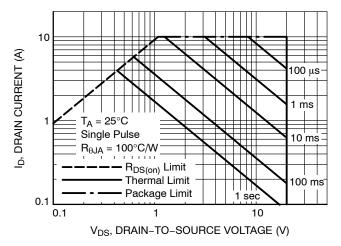


Figure 12. Safe Operating Area (SOA)



## **MECHANICAL CASE OUTLINE**

**MILLIMETERS** 

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40

\_\_\_

PACKAGE DIMENSIONS



#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

**DATE 14 AUG 2024** 

MAX

1.11

0.10

0.50

0.20

3.04

1.40

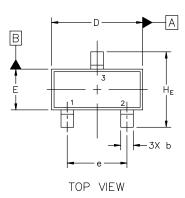
2.04

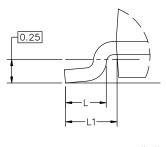
0.55

0.69

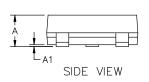
2.64

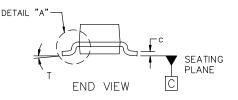
10°





DETAIL "A" Scale 3:1





### 2.90 3X 0.95 3X 0.56-0.95 PITCH

#### NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Т

- DIMENSIONING AND TOLERANCING 1.
- PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

#### RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **STYLES ON PAGE 2**

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<sup>\*</sup>This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

#### SOT-23 (TO-236) 2.90x1.30x1.00 1.90P CASE 318 ISSUE AU

DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7:         STYLE 8:           PIN 1. EMITTER         PIN 1. ANOD           2. BASE         2. NO CC           3. COLLECTOR         3. CATHO	ONNECTION	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11:         STYLE 12:           PIN 1.         ANODE         PIN 1.         CATHO           2.         CATHODE         2.         CATHO           3.         CATHODE-ANODE         3.         ANODO	ODE 2. DRAIN 2. GATE	
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17:         STYLE 18:           PIN 1. NO CONNECTION         PIN 1. NO CO           2. ANODE         2. CATHO           3. CATHODE         3. ANODO	ODE 2. ANODE 2. ANODE	
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23:         STYLE 24:           PIN 1. ANODE         PIN 1. GATE           2. ANODE         2. DRAIN           3. CATHODE         3. SOURCE		CTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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